

LAB

What's new v5.10

What's New LAB 5.10



Simplified CAR Model



Simplified CAR Model

- CAR resist modelling requires a Post Exposure Bake (PEB) process simulation. The complete parameter set in older LAB versions are kept in the Full model.
- The new simple CAR model removes PEB temperature dependence and reduces the PEB parameters to only three:
 - Acid diffusivity
 - PEB amplification
 - Quencher loading
- Simple CAR model facilitates resist calibration while valid for many resists.

Resist Type						
O DNQ		CAR				
			_			
CAR Model						
Simple	Full					
Acid Diffusivi	tv [nm^2/s] 0	.000000]			
]			
PEB Amplific	ation [1/s]	.000000				
Quencher Lo	ading 0	.150000]			
Rmin [um/s]	0.000132			Rmax [um/s]	2.036000	
Rmin [µm/s]	0.000132			Rmax [µm/s]	2.036000	
Rmin [µm/s] Slope	0.000132			Rmax [µm/s] Mth	2.036000	
Slope						
Slope Resist Tone	35.212000					
Slope						
Slope Resist Tone Positive	35.212000					
Slope Resist Tone Positive Depth Mode	35.212000			Mth		
Slope Resist Tone Positive	35.212000	() Surfac	:e inhibitic	Mth		
Slope Resist Tone Positive Depth Mode None	35.212000	-		Mth		
Slope Resist Tone Positive Depth Mode	35.212000	○ Surfac		Mth		
Slope Resist Tone Positive Depth Mode None	35.212000	-	0.25000	Mth		



Rule OPC Optimizer

What's New LAB 5.10



OPC Rule Optimization

Critical Shape Error (CSE) is activated for optimization of OPC rules.

- CSE is the average deviation between the simulated contour and target contour. CSE = 0 means no difference between the resulting shape and target.
- CSE for each OPC rule is calculated as well as a total CSE for all applied OPC rules.
- Please refer to the LAB manual for CSE definition in details.

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Min Corner Size [um]		0.150000		Max Segment Size [um] 1000000.00000		000				ptimizer R	lesult				-		
Bias Limit [um]		0.000000									OPC Simulated Contour						
Target Layer		OPC															
Action	Depende	ence Param	Scenario	Con	dition	Optimize	CSE [nm]										
Bias	CD		nySegment	true			13		Insert								
Serif	-	C	orner	true			13		Delete								
									Up								
									Up Down								
Condition		true															
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Type of Serif Min Edge Leng Min Distance [Size [um]] gth [um]	Manhattan 0.010000 0.055000 %[0.05:0.2]((0.141868)%		size	erlap	-										
Type of Serif Min Edge Leng Min Distance [Size [um]] gth [um]	Manhattan 0.010000 0.055000 %[0.05:0.2]((0.141868)%			erlap	-										
Type of Serif Min Edge Leng Min Distance [Size [um]] gth [um]	Manhattan 0.010000 0.055000 %[0.05:0.2]((0.141868)%			erlap	-				All	Hide	Sh	IOW	Cell Inform	ation	Me
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Improved Resist Calibration



In Resist Calibration, *Ensure Clearing* adds a condition to ensure a proper resist profile

- Previously the only condition was a CD measurement not considering the resist shape above or below the measurement line
- With this new condition, only clearing parameter sets are considered as solution

Resist Clearing in Calibration

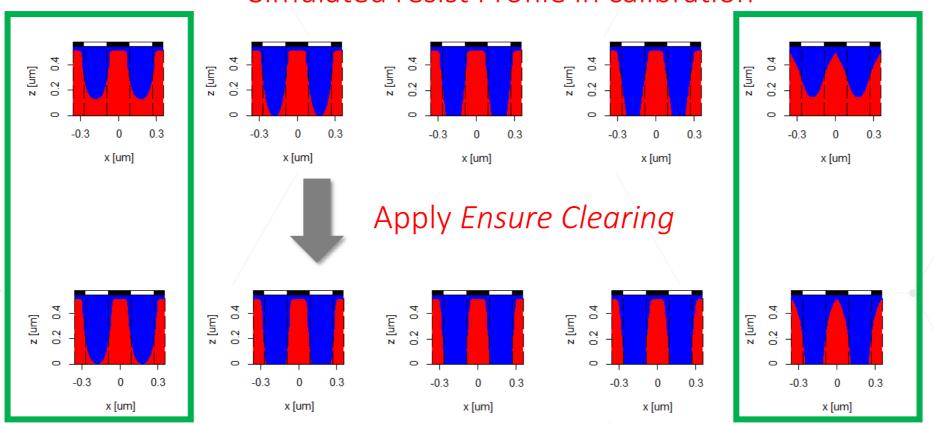
Resist Calib								
Settings L	.abel/Comment							
Setting	gs	FEM 1 <add< td=""><td>></td><td></td><td></td><td></td><td></td><td></td></add<>	>					
P	rojection	Measurement	5					
	Resist	v Defocus v						
)ptimizer	[um]	[um]	[um]	[um]	[um]		
⊡ En	isure Clearing		0.15309	0.12666	0.11255	0.08417		
Calibra	ation	0.35	1	1	1	1		
	Run	0.3	0.14745	0.12883	0.11551	0.10293		
		0.5	1	1	1	1		
Re	esult View	0.25	0.14376	0.1295	0.1189	0.10848		
Sav	ve Material	0.25	1	1	1	1		
001	Verification View	0.2	0.1426	0.13044	0.11951	0.10865		
Verifica		0.2	1	1	1	1		
V		0.15	0.1429	0.12884	0.11753	0.10797		
			1	1	1	1		
		0.1	0.14254	0.12841	0.11641	0.10548		
		0.1	1	1	1	1		
		Create Emp	oty Imp	port Data	Export	Data	Reset	De



Resist Clearing in Calibration

Example of resist clearing in calibration

• The condition "ensure clearing" is fulfilled, if the resist contour touches the substrate surface in at least on position within the simulation region.



Simulated resist Profile in calibration



Topogaphy Stack 3D View



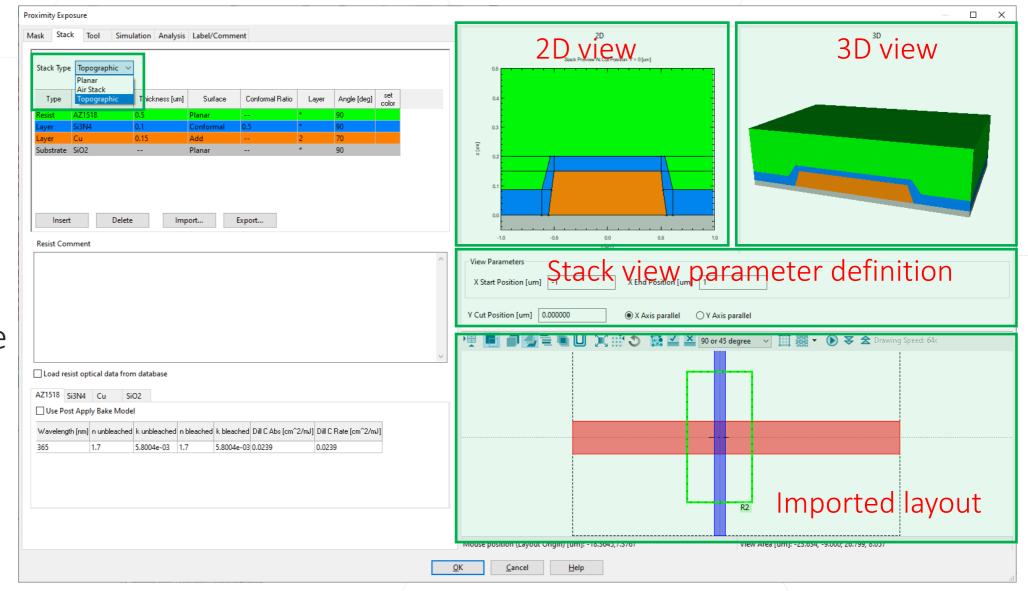
Topography Stack 3D View

3D view of topography stack

• The stack 3D view is available after importing the layout.

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Proxin	nity 💌

• Selection of Stack Type "Topographic" opens the viewer.

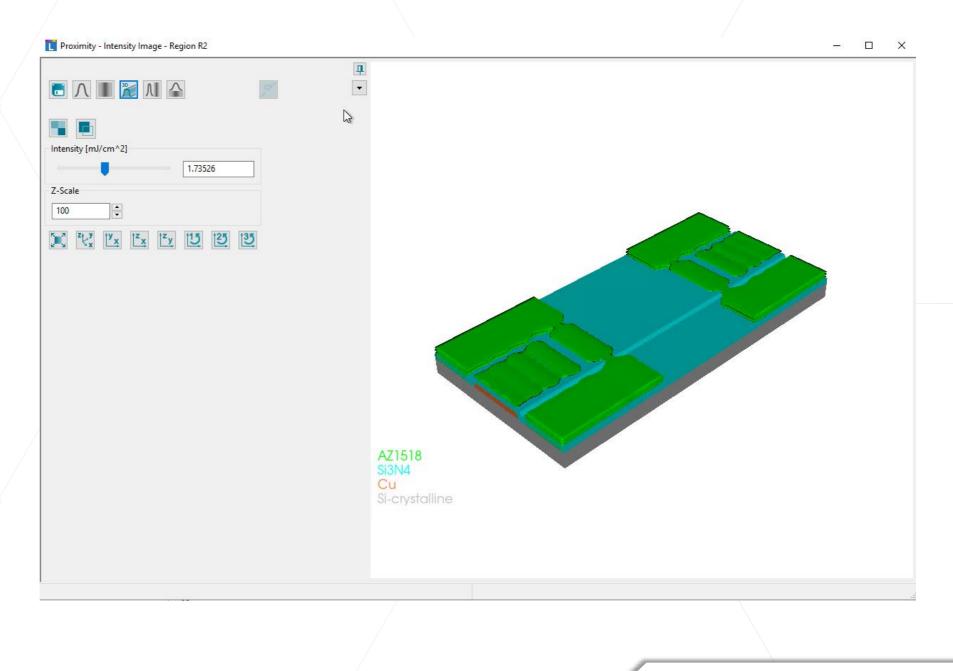




Result 3D View

3D view of topography result

 3D images of both bulk intensity and resist profile are available





Thick Resist Simulation



Incoherent Z Averaging

- Thick resist simulation has a heavy demands on memory and simulation time.
- This requires a relative large Grid Z value, which can cause sampling errors in cases with standing wave effects.
- Incoherent Z averaging is introduced to suppress the standing wave effect while keeping high accuracy in intensity simulation.

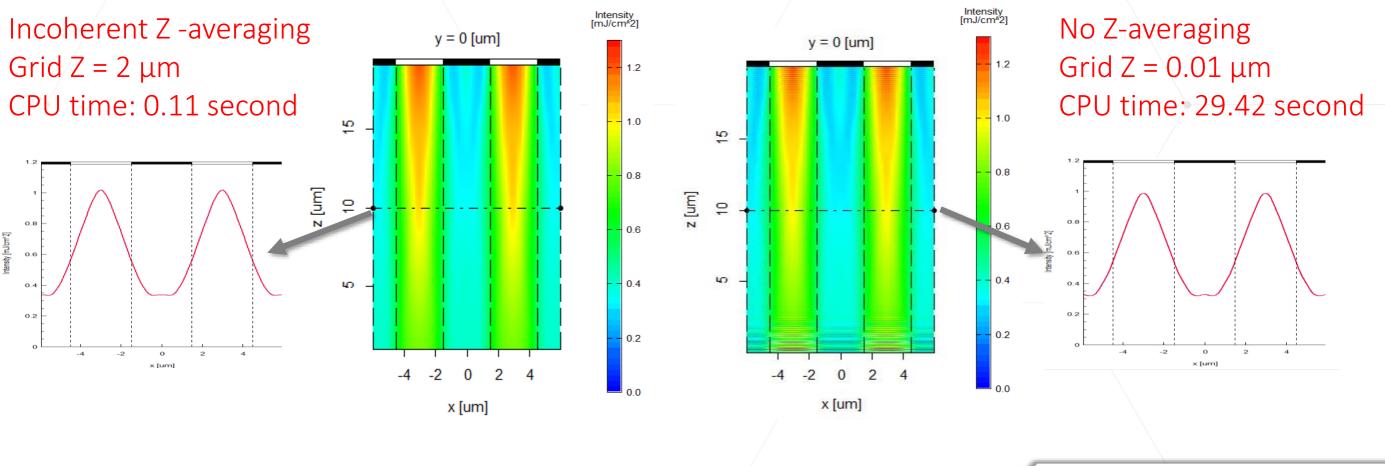
Mask	Stack	Tool	Simulation	Analysis	Label/Comment			
Grid	X/Y [um]	0.1000	00					
Grid	Z [um]	0.0500	00					
Verti	ical range							
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	ion Period eriodic	0 incohere 2 4	ent					
Regi	ion Period	licity in Y						
P	eriodic	0	Non-periodic					
	uence Ran utomatic	_	inual			Influen	ice Range [um]	0.200000



Incoherent Z-Averaging

Simulation example for SU8 with 20 μm thickness

- Incoherent Z-averaging has comparable simulation result with no Z-averaging, with intensity deviation within 3.3%.
- Incoherent Z-averaging significantly reduces simulation time.





BEAMER

Thank You!

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VIEWER

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